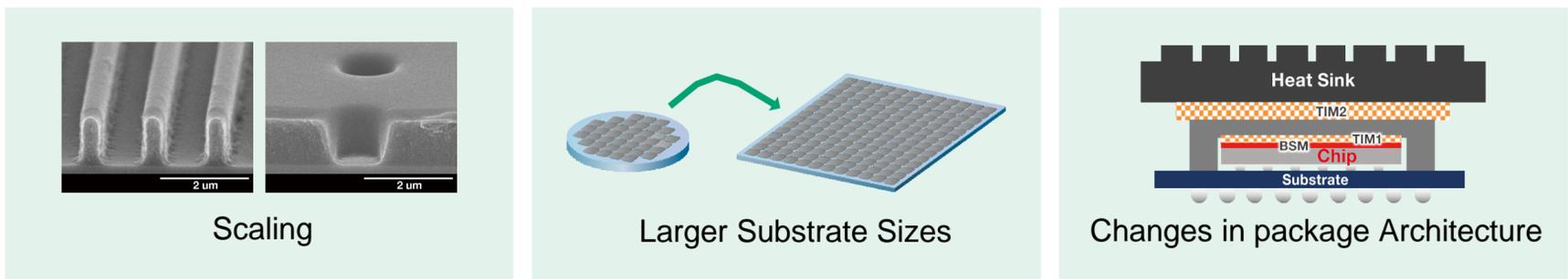


# Heat Dissipation Materials

FUJIFILM contributes to the advancement of semiconductor devices by introducing novel thermal management materials that address the heat challenges arising from higher integration and advanced stacking architectures.

## Evolving customer manufacturing requirements

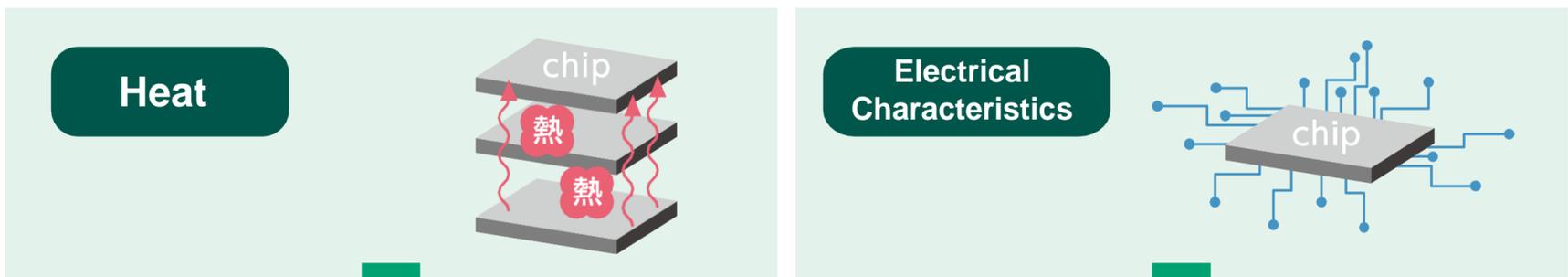
The stacking of multiple chips in driving changes in advanced packaging manufacturing process



## Performance requirement changes

Higher integration reduces available heat dissipation paths, leading to increased thermal confinement.

Higher integration results in narrower interconnects, which degrades electrical efficiency.



**Thermal Interface Material**

**Dielectric Layer**

We intend to offer materials that meet evolving market needs, covering thermal solutions for both traditional power devices and advanced packaging applications.

